

WHAT IS CLAIMED IS:

1. A conductive paste comprising:  
a conductive component;  
a glass frit comprising a  $\text{Bi}_2\text{O}_3\text{-B}_2\text{O}_3\text{-SiO}_2\text{-Al}_2\text{O}_3$  or  $\text{Bi}_2\text{O}_3\text{-B}_2\text{O}_3\text{-SiO}_2\text{-Al}_2\text{O}_3\text{-ZnO}$  glass as primary component and about 0.5 to 5% by weight of NiO as a  
5 secondary component; and  
an organic vehicle.
2. A conductive paste according to claim 1, wherein the glass contains about 60 to 85% by weight of  $\text{Bi}_2\text{O}_3$ , about 3 to 10% by weight of  $\text{B}_2\text{O}_3$ , about 2 to 15% by weight of  $\text{SiO}_2$ , about 3 to 7% by weight of  $\text{Al}_2\text{O}_3$ , and 0 to about 15% by weight of ZnO.
3. A conductive paste according to claim 2, wherein the conductive component is at least one of silver, silver-palladium, platinum, gold, and rhodium.
4. A conductive paste according to claim 3, further comprising about 2% by weight or less of at least one of alumina, amorphous silica and  $\text{MoSi}_2$ .
5. A conductive paste according to claim 4, wherein the conductive component is a metal powder having a mean particle size of less than about 20  $\mu\text{m}$ .
6. A conductive paste according to claim 5, wherein the metal powder has a mean particle size of about 0.1 to 10  $\mu\text{m}$ .
7. A conductive paste according to claim 6, wherein the metal powder has a mean particle size of about 0.1 to 6  $\mu\text{m}$ .
8. A conductive paste according to claim 1, wherein the conductive component is at least one of silver, silver-palladium, platinum, gold, and rhodium.

9. A conductive paste according to claim 1, further comprising about 2% by weight or less of at least one of alumina, amorphous silica and MoSi<sub>2</sub>.
10. A conductive paste according to claim 1, wherein the conductive component is a metal powder having a mean particle size of less than about 20 μm.
11. A conductive paste according to claim 10, wherein the metal powder has a mean particle size of about 0.1 to 10 μm.
- 5 12. A conductive paste according to claim 10, wherein the metal powder has a mean particle size of about 0.1 to 6 μm.
13. A conductive paste according to claim 1, further comprising a resistance adjuster.
14. A conductive paste according to claim 1, disposed on a glass substrate  
10 in a conductor circuit pattern.
15. A glass circuit structure comprising:  
a glass substrate; and  
a conductor circuit comprising a conductor film on the glass substrate;  
wherein the conductor film is a baked conductive paste according to  
15 claim 1.
16. A glass circuit structure according to claim 15, wherein the glass substrate is a defogging glass of an automobile window.
17. A glass circuit structure comprising:  
5 a glass substrate; and  
a conductor circuit comprising a conductor film on the glass substrate;  
wherein the conductor film is a baked conductive paste according to  
claim 4.

18. A glass circuit structure according to claim 15, wherein the glass substrate is a defogging glass of an automobile window.

5 19. A glass circuit structure comprising:  
a glass substrate; and  
a conductor circuit comprising a conductor film on the glass substrate;  
wherein the conductor film is a baked conductive paste according to  
claim 5.

20. A glass circuit structure according to claim 19, wherein the glass substrate is a defogging glass of an automobile window.